FRONTGRADE DATASHEET UT54ACS00/UT54ACTS00

Quadruple 2-Input NAND Gates

11/1/2010 Version #: 1.0

Version #: 1.0

Quadruple 2-Input NAND Gates

11/1/2010

Features

- 1.2μ CMOS
 - > Latchup immune
- High speed
- Low power consumption
- Single 5 volt supply
- Available QML Q or V processes
- Flexible package
 - > 14-pin DIP
 - > 14-lead flatpack
- UT54ACS00 SMD 5962-96512
- UT54ACTS00 SMD 5962-96513

Description

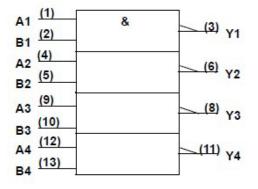
The UT54ACS00 and the UT54ACTS00 are quadruple, two input NAND gates. The circuits perform the Boolean functions $Y = \overline{A} \cdot \overline{B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The devices are characterized over full military temperature range of -55°C to +125°C.

Function Table

Inp	Output	
А	В	Υ
н	Н	L
L	X	Н
X	L	Н

Logic Symbol

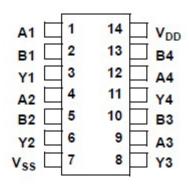


Note:

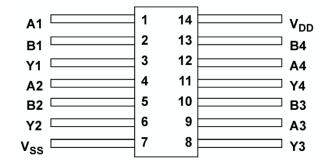
1. Logic symbol in accordance with ANSI/IEEE standard 91-1984 and IEC Publication 617-12.

Version #: 1.0

Pinouts

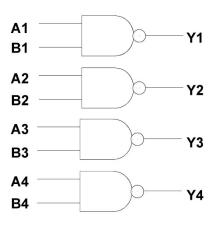








Logic Diagram



UT54ACS00/UT54ACTS00

Quadruple 2-Input NAND Gates

11/1/2010

Quadruple 2-Input NAND Gates

11/1/2010

Operational Environment¹

Parameter	Limit	Units
Total Dose	1.0E6	rads(Si)
SEU Threshold ²	80	MeV-cm ² /mg
SEL Threshold	120	MeV-cm ² /mg
Neutron Fluence	1.0E14	n/cm ²

Notes:

- 1. Logic will not latchup during radiation exposure within the limits defined in the table.
- 2. Device storage elements are immune to SEU affects.

Absolute Maximum Ratings

Symbol	Parameter	Limit	Units
V _{DD}	Supply voltage	-0.3 to 7.0	v
V _{I/O}	Voltage any pin	3 to V _{DD} +.3	V
T _{STG}	Storage Temperature range	-65 to +150	°C
Тյ	Maximum junction temperature	+175	°C
T _{LS}	Lead temperature (soldering 5 seconds)	+300	°C
θ _{JC}	Thermal resistance junction to case	20	°C/W
lı	DC input current	±10	mA
P _D	Maximum power dissipation	1	w

Note:

1. Stresses outside the listed absolute maximum ratings may cause permanent damage to the device. This is a stress rating only, functional operation of the device at these or any other conditions beyond limits indicated in the operational sections is not recommended. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Limit	Units
V _{DD}	Supply voltage	4.5 to 5.5	V
V _{IN}	Input voltage any pin	0 to V_{DD}	V
Tc	Temperature range	-55 to + 125	°C

11/1/2010

DC Electrical Characteristics⁷

 $(V_{DD} = 5.0V \pm 10\%; V_{SS} = 0V^6, -55 \degree C < T_C < +125\degree C)$; Unless otherwise noted, T_C is per the temperature range ordered.

Symbol	Parameter	Condition	MIN	MAX	Unit
V _{IL}	Low-level input voltage ¹ ACTS ACS			0.8 .3V _{DD}	v
V _{IH}	High-level input voltage ¹ ACTS ACS		.5V _{DD} .7V _{DD}		v
l _{iN}	Input leakage current ACTS/ACS	V _{IN} = V _{DD} or V _{SS}	-1	1	μA
V _{OL}	Low-level output voltage ³ ACTS ACS	I _{OL} = 8.0mA I _{OL} = 100 μA		0.40 0.25	v
V _{OH}	High-level output voltage ³ ACTS ACS	I _{OH} = -8.0mA I _{OH} = -100 μA	.7V _{DD} V _{DD} - 0.25		v
I _{OS}	Short-circuit output current ^{2,4} ACTS/ACS	$V_{O} = V_{DD}$ and V_{SS}	-200	200	mA
IOL	Output current ¹⁰ (Sink)	$V_{IN} = V_{DD} \text{ or } V_{SS}$ $V_{OL} = 0.4V$	8		mA
I _{он}	Output current ¹⁰ (Source)	$V_{IN} = V_{DD} \text{ or } V_{SS}$ $V_{OH} = V_{DD} - 0.4V$	-8		mA
P _{total}	Power dissipation ^{2,8,9}	C _L = 50pF		1.8	mW/ MHz
I _{DDQ}	Quiescent Supply Current	V _{DD} = 5.5V		10	μA
ΔI _{DDQ}	Quiescent Supply Current Delta ACTS	For input under test $V_{IN} = V_{DD} - 2.1V$ For all other inputs $V_{IN} = V_{DD}$ or $V_{SS} V_{DD} = 5.5V$		1.6	mA
C _{IN}	Input capacitance ⁵	f = 1MHz @ 0V		15	pF
C _{OUT}	Output capacitance ⁵	f = 1MHz @ 0V		15	pF

Notes:

- 1. Functional tests are conducted in accordance with MIL-STD-883 with the following input test conditions: $V_{IH} = V_{IH}(min) + 20\%$, 0%; $V_{IL} = V_{IL}(max) + 0\%$, 50%, as specified herein, for TTL, CMOS, or Schmitt compatible inputs. Devices may be tested using any input voltage within the above specified range, but are guaranteed to $V_{IH}(min)$ and $V_{IL}(max)$.
- 2. Supplied as a design limit but not guaranteed or tested.
- Per MIL-PRF-38535, for current density ≤5.0E5 amps/cm², the maximum product of load capacitance (per output buffer) times frequency should not exceed 3,765 pF/MHz.
- 4. Not more than one output may be shorted at a time for maximum duration of one second.
- 5. Capacitance measured for initial qualification and when design changes may affect the value. Capacitance is measured between the designated terminal and V_{SS} at frequency of 1MHz and a signal amplitude of 50mV rms maximum.
- 6. Maximum allowable relative shift equals 50mV.
- 7. All specifications valid for radiation dose ≤1E6 rads(Si).
- 8. Power does not include power contribution of any TTL output sink current.
- 9. Power dissipation specified per switching output.
- 10. This value is guaranteed based on characterization data, but not tested.

11/1/2010

AC Electrical Characteristics²

 $(V_{DD} = 5.0V \pm 10\%; V_{SS} = 0V^1, -55^{\circ}C < T_C < +125^{\circ}C)$; Unless otherwise noted, T_c is per the temperature range ordered.

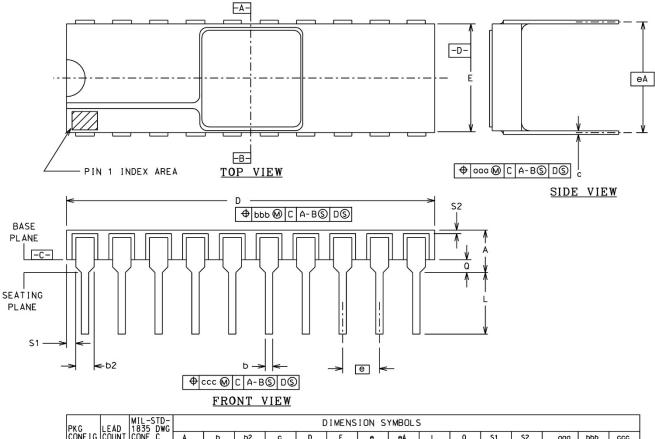
Symbol	Parameter	Minimum	Maximum	Unit
t _{PHL}	Input to Yn	1	14	ns
t _{PLH}	Input to Yn	1	11	ns

Notes:

- 1. Maximum allowable relative shift equals 50mV.
- 2. All specifications valid for radiation dose ≤1E6 rads(Si).

Packaging

Side-Brazed Packages



PKG	LEAD	1835 DWG		DIMENSION SYMBOLS													
CONF I G	COUNT	CONF C	A	Þ	b2	с	D	E	е	eA	L	0	S1	S2	مەت	bbb	ccc
-01	14	D-1	0.200	0.026	0.065	0.018	0.785	0.310	0.100	0.300	0.200	0.060			0.015	0.030	0.010
01				0.014	0.045	0.008		0.220	BSC	BSC	0.125	0.015	0.005	0.005			
-02	16	D-2	0.200	0.026	0.065	0.018	0.840	0.310	0.100	0.300	0.200	0.060			0.015	0.030	0.010
02	10	02		0.014	0.045	0.008		0.220	BSC	BSC	0.125	0.015	0.005	0.005			
-03	20	D-8	0.200	0.026	0.065	0.018	1.060	0.310	0.100	0.300	0.200	0.070			0.015	0.030	0.010
05	20	0 0		0.014	0.045	0.008		0.220	BSC	BSC	0.125	0.015	0.005	0.005			

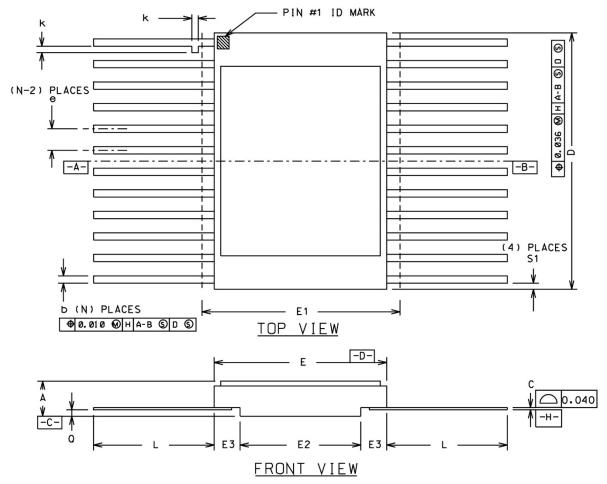
Version #: 1.0

UT54ACS00/UT54ACTS00

Quadruple 2-Input NAND Gates

11/1/2010

Flatpack Packages



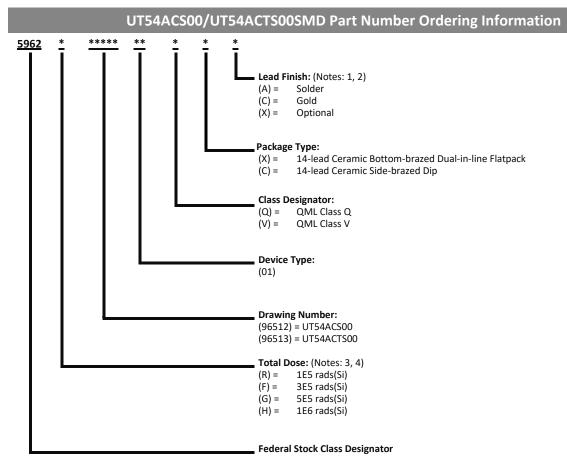
PKG	LEAD	MIL-STD 1835 DWG		DIMENSION SYMBOLS											
CONFIG	COUNT	CONF B	Α	b	С	D	E	E1	E2	E 3	е	k	L	Q	S1
-03	14	F-2A	0.115	0.022	0.009	0.390	0.260	0.290			0.050	0.015	0.370	0.045	
-03	14	F-ZA	0.045	0.015	0.004		0.235		0.130	0.030	BSC	0.008	0.270	0.026	0.005
-04	16	F-5A	0.115	0.022	0.009	0.440	0.285	0.315			0.050	0.015	0.370	0.045	
-04	10	F-JA	0.045	0.015	0.004		0.245		0.130	0.030	BSC	0.008	0.250	0.026	0.005
-05	20	F-9A	0.115	0.022	0.009	0.540	0.300	0.330			0.050	0.015	0.370	0.045	
-05	20	F-JA	0.045	0.015	0.004		0.245		0.130	0.030	BSC	0.008	0.250	0.026	0.000

Version #: 1.0

Quadruple 2-Input NAND Gates

11/1/2010





Notes:

- 1. Lead finish (A, C or X) must be specified.
- 2. If an "X" is specified when ordering, part marking will match the lead finish and will be either "A" (solder) or "C" (gold).
- 3. Total dose radiation must be specified when ordering. QML Q and QML V not available without radiation hardening. For prototype inquiries, contact factory.
- 4. Device type 02 is only offered with a TID tolerance guarantee of 3E5 rads(Si) or 1E6 rads(Si) and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A and section 3.11.2. Device type 03 is only offered with a TID tolerance guarantee of 1E5 rads(Si), 3E5 rads(Si), and 5E5 rads(Si), and is tested in accordance with MIL-STD-883 Test Method 1019 Condition A.

Quadruple 2-Input NAND Gates

11/1/2010

Revision History

Date	Revision #	Author	Change Description	Page #

Datasheet Definitions

	Definition
Advanced Datasheet	Frontgrade reserves the right to make changes to any products and services described herein at any time without notice. The product is still in the development stage and the datasheet is subject to change . Specifications can be TBD and the part package and pinout are not final .
Preliminary Datasheet	Frontgrade reserves the right to make changes to any products and services described herein at any time without notice. The product is in the characterization stage and prototypes are available.
Datasheet	Product is in production and any changes to the product and services described herein will follow a formal customer notification process for form, fit or function changes.

Frontgrade Technologies Proprietary Information Frontgrade Technologies (Frontgrade or Company) reserves the right to make changes to any products and services described herein at any time without notice. Consult a Frontgrade sales representative to verify that the information contained herein is current before using the product described herein. Frontgrade does not assume any responsibility or liability arising out of the application or use of any product or service described herein, except as expressly agreed to in writing by the Company; nor does the purchase, lease, or use of a product or service convey a license to any patents rights, copyrights, trademark rights, or any other intellectual property rights of the Company or any third party.